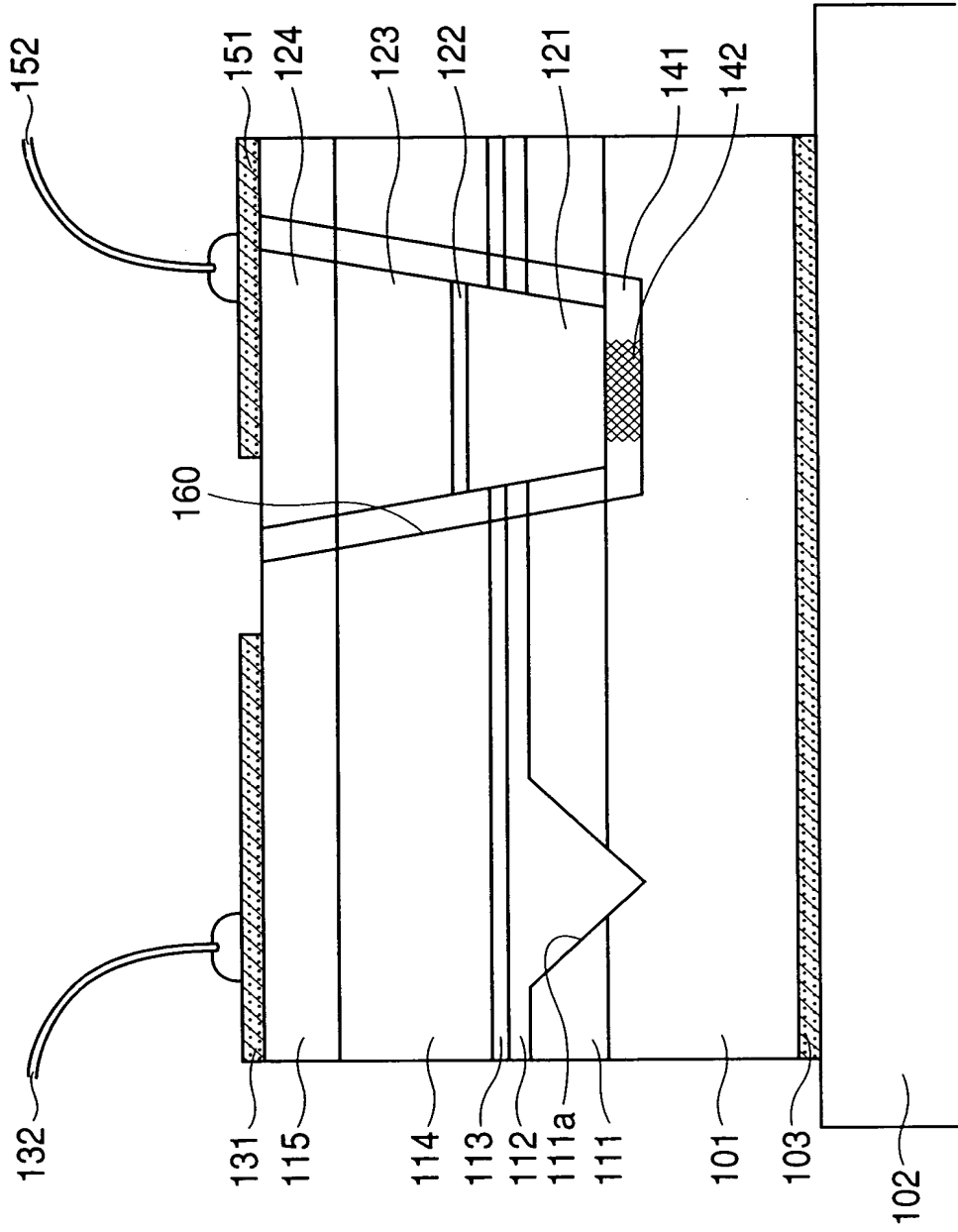


002020-2065-150

APPROVED	O.G. FIG.	
BY	CLASS	SUBCLASS
DRAFTSMAN		

FIG. 1



APPROVED	O.G. FIG.	
BY	CLASS	SUBCLASS
DRAFTSMAN		

FIG. 2(a)

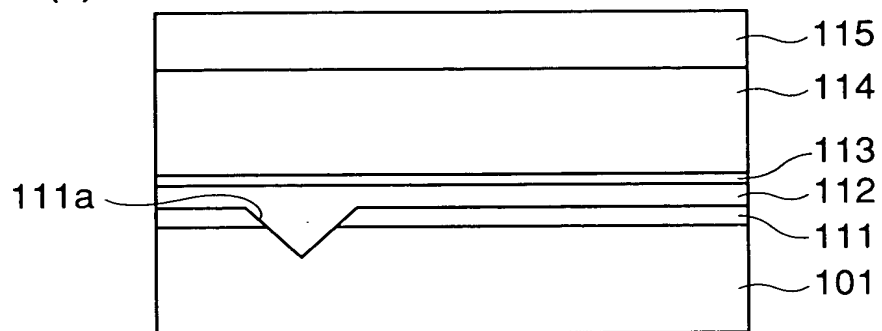


FIG. 2(b)

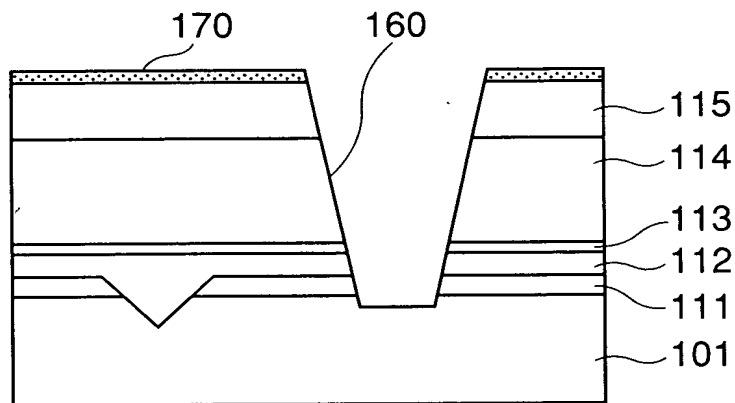
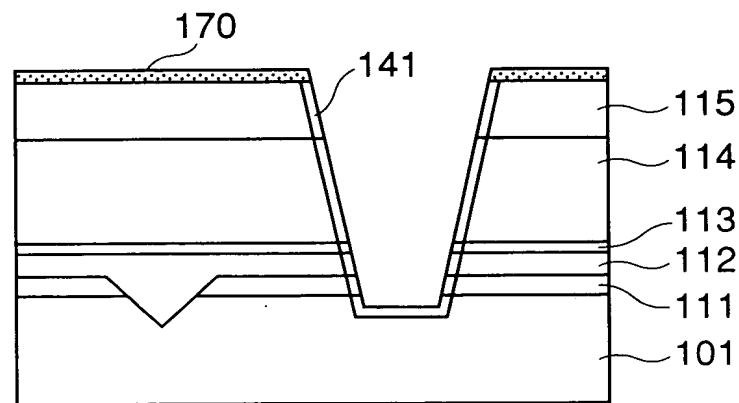


FIG. 2(c)



004020-2006460

[illegible]

3(e)

170

115

114

113

112

111

101

124

123

122

121

This diagram shows a cross-sectional view of a semiconductor device. It features a substrate 101 with a series of horizontal layers 111, 112, 113, 114, and 115. A trench is formed in the substrate, with a bottom layer 121 and upper layers 122, 123, and 124. A top layer 170 is positioned above the trench. The layers 111, 112, 113, 114, and 115 are shown as horizontal lines, while the layers 121, 122, 123, and 124 are shown as horizontal lines within the trench. The layer 170 is shown as a horizontal line above the trench. The layers 111, 112, 113, 114, and 115 are shown as horizontal lines, while the layers 121, 122, 123, and 124 are shown as horizontal lines within the trench. The layer 170 is shown as a horizontal line above the trench.

3(f)

132, 152, 131, 151, 115, 124, 114, 123, 113, 122, 112, 121, 111, 103, 102

This cross-sectional view shows a semiconductor device with a substrate 102. A trench is formed in a layer 101, with a bottom layer 121 and a top layer 124. The trench is filled with a material 122. The trench is bounded by a layer 111, which is part of a stack of layers 111, 112, 113, 114, 115. The top surface of the device is covered by a layer 131, with contacts 132 and 152. A layer 151 is also present on the top surface.

APPROVED	O.G. FIG.	
BY	CLASS	SUBCLASS
DRAFTSMAN		

004020-2066460

FIG. 4

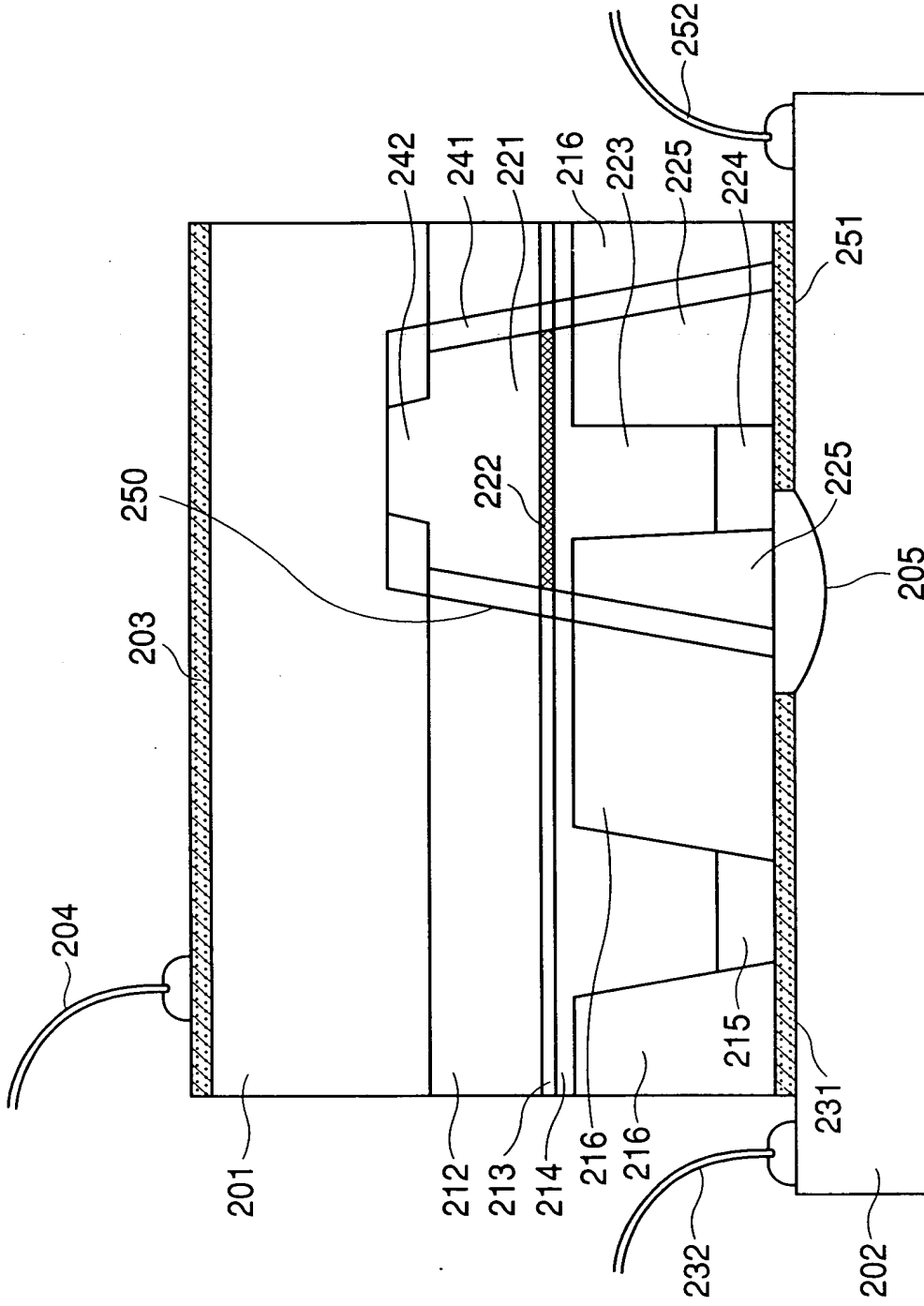


FIG. 5(a)

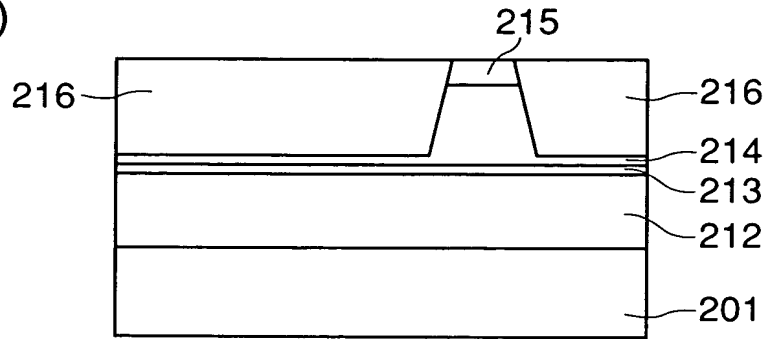


FIG. 5(b)

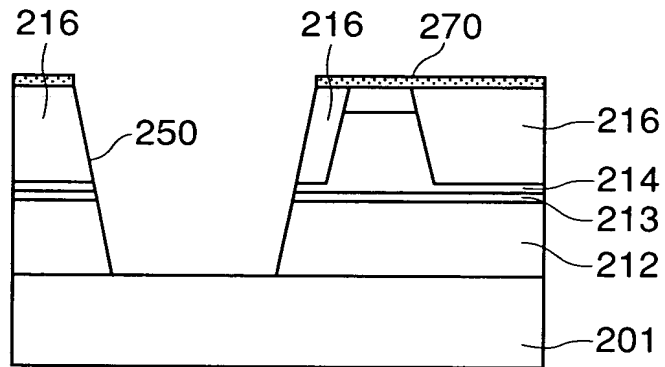


FIG. 5(c)

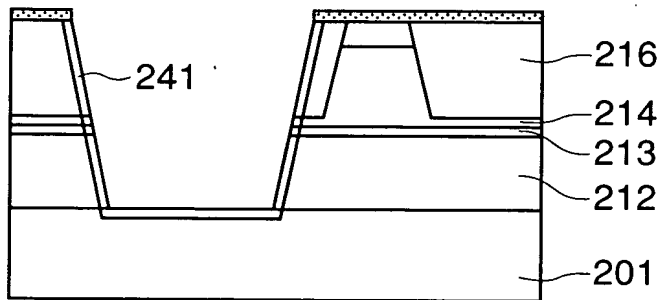
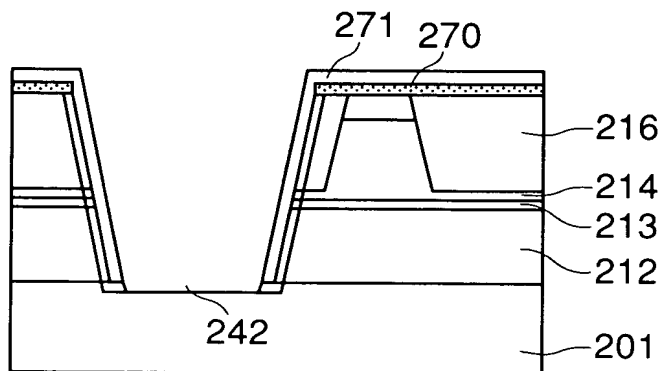


FIG. 5(d)





APPROVED	O.G. FIG.	
BY	CLASS	SUBCLASS
DRAFTSMAN		

004020-22065460

FIG. 7

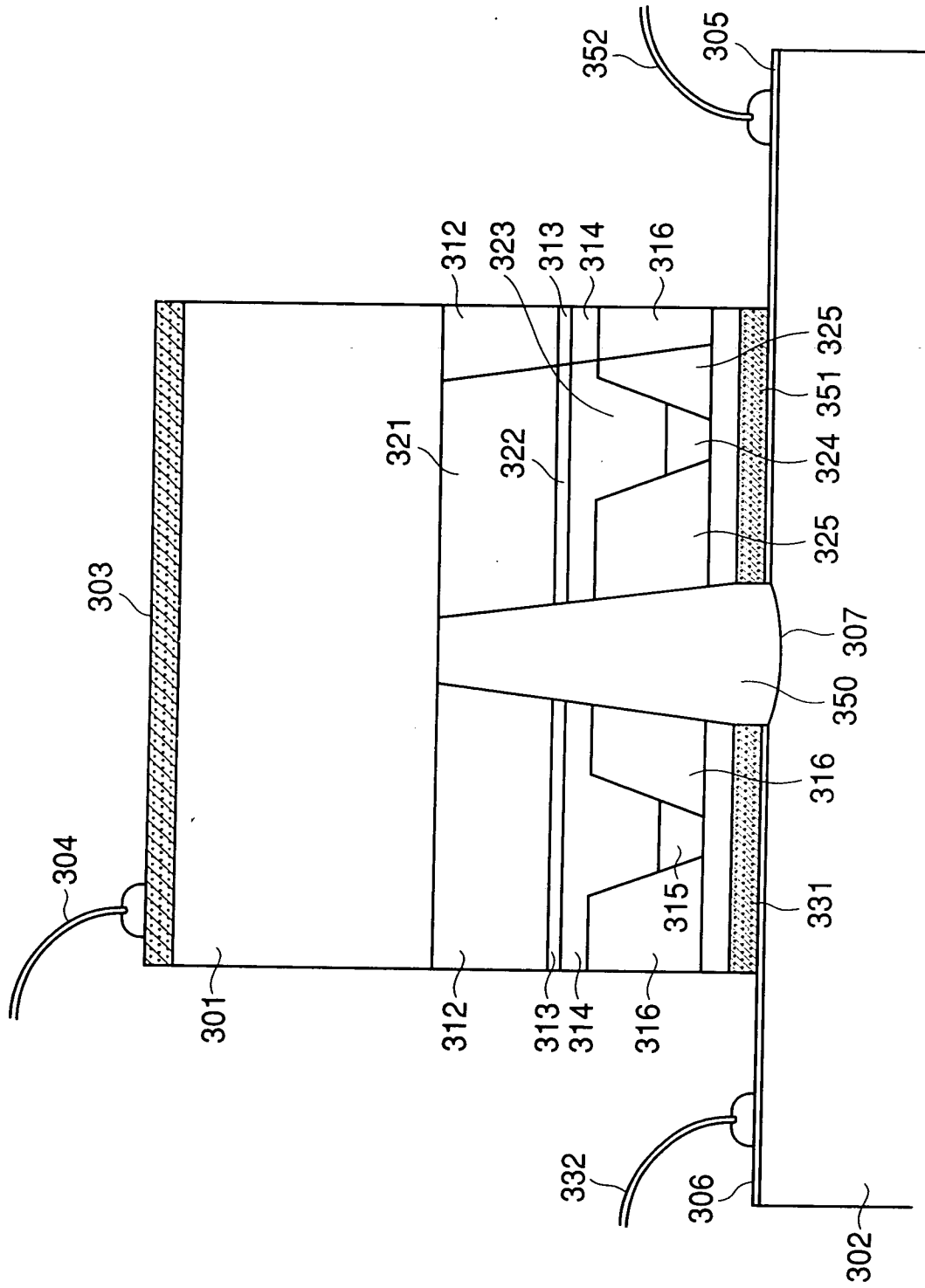


FIG. 8(a)

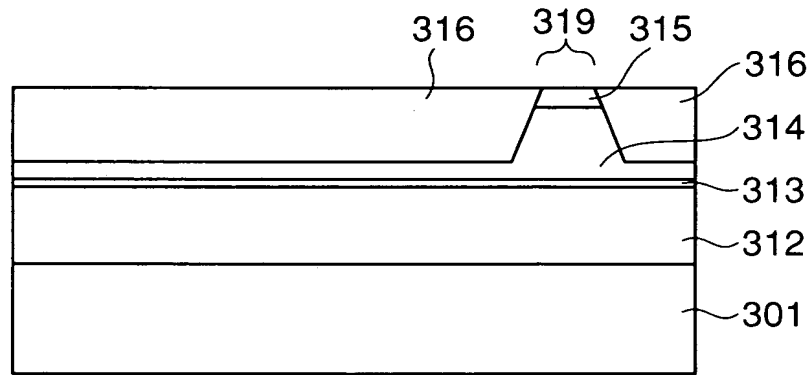


FIG. 8(b)

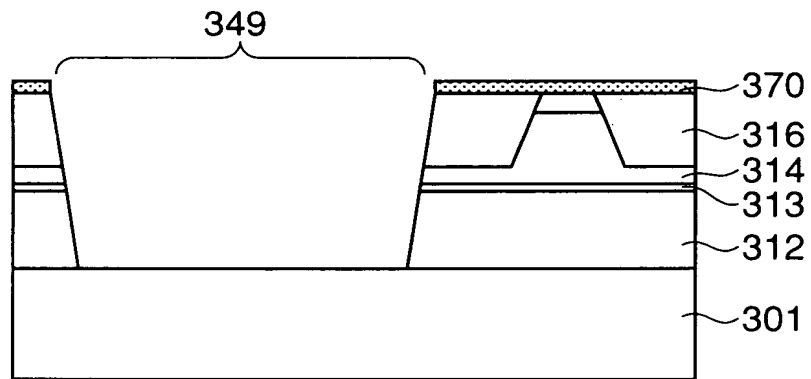


FIG. 8(c)

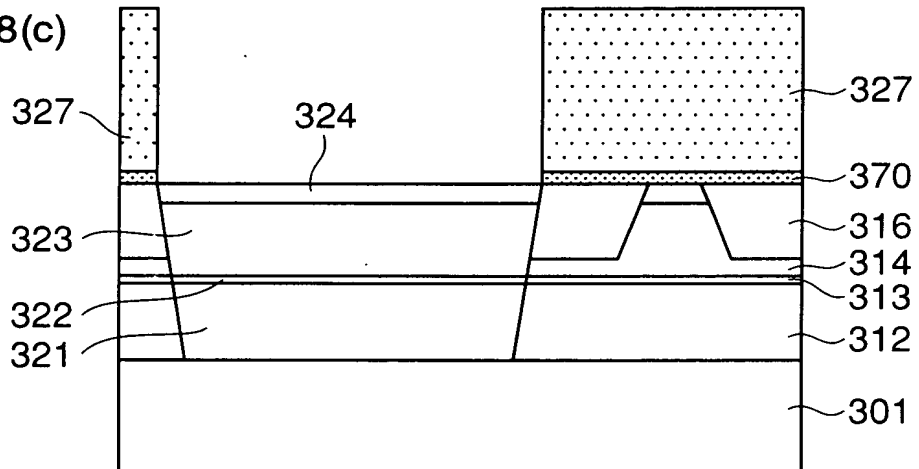
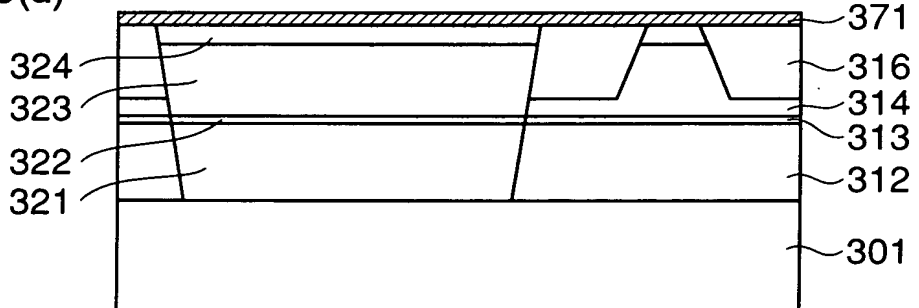
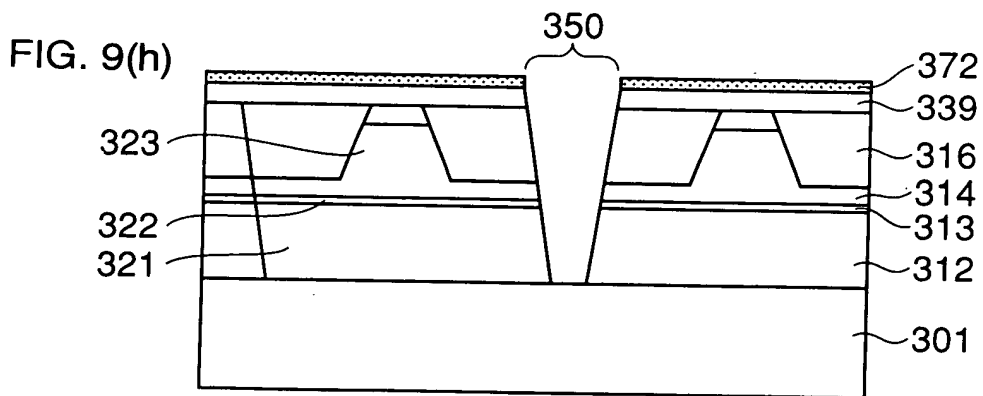
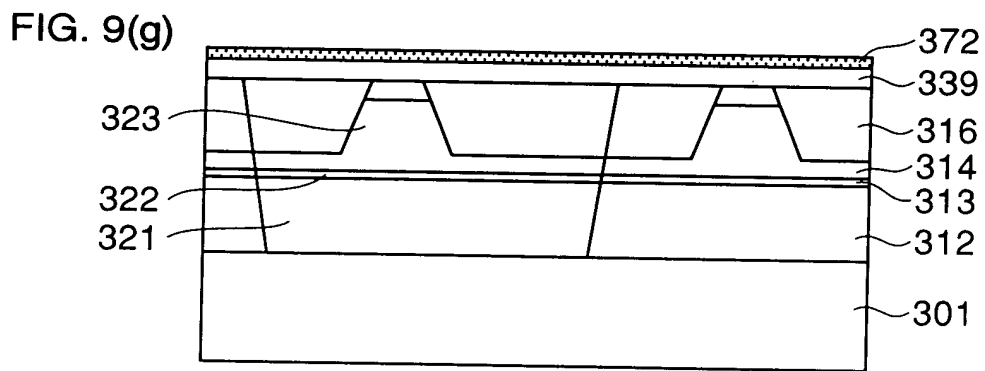
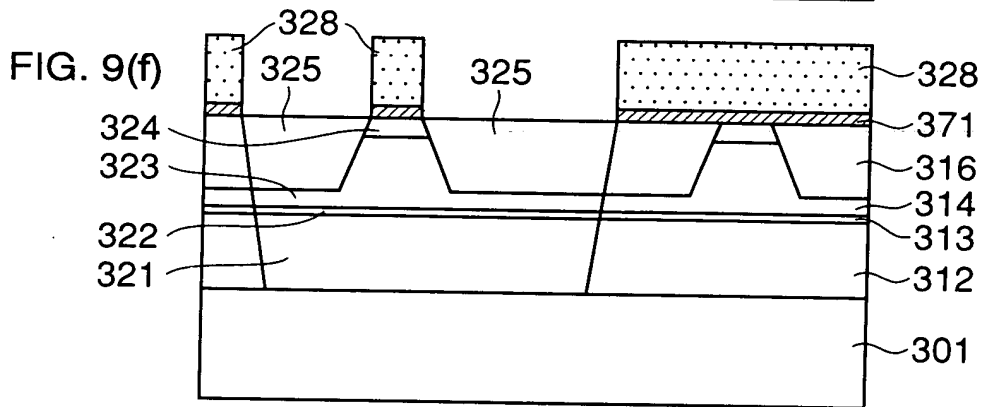
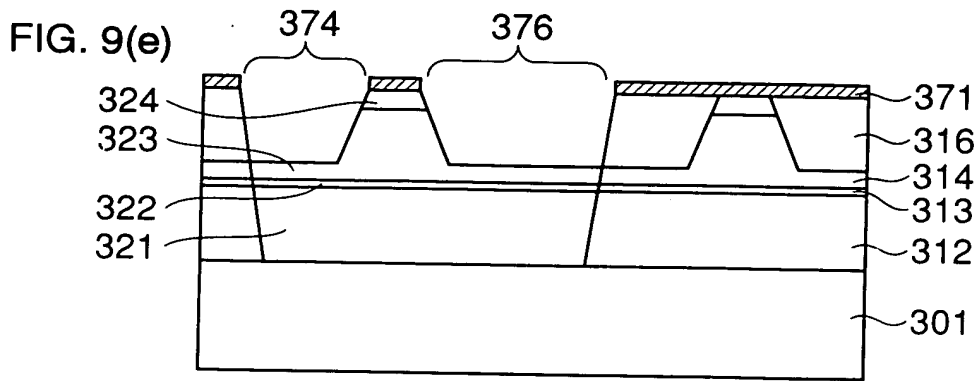


FIG. 8(d)



002020 20060600





004020 2006060

002020 22066460

APPROVED BY DRAFTSMAN	O.G. FIG.
CLASS	SUBCLASS

FIG. 10

